

ABSTRACT

A system comprising a first robotic arm assembly for capturing and releasing a semiconductor wafer, a second robotic arm for capturing and releasing an interleaf, and a controller for actuation of the first and second robotic arms, the first and second robotic arms operating substantially simultaneously. At least one robotic arm can include a transfer arm, and a counterweight attached to a first end of the transfer arm and an end effector attached to a second, opposite end of the transfer arm. Two robotic arms permit the system to carry out the steps substantially simultaneously and therefore increase throughput significantly.

20707708.doc